MA3X748 (MA748)

Silicon epitaxial planar type

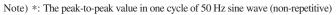
For high frequency rectification

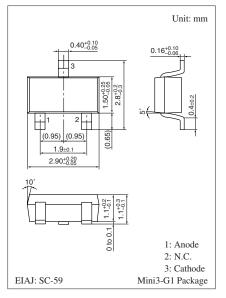
Features

- Low V_F type of MA3X720 (MA720)
- \bullet Low forward voltage $V_{\rm F}$ and good rectification efficiency
- \bullet Optimum for high frequency rectification because of its short reverse recovery time $t_{\rm rr}$

Absolute Maximum Ratings $T_a = 25^{\circ}C$						
Parameter	Symbol	Rating	Unit			
Reverse voltage	V _R	20	V			
Repetitive peak reverse voltage	V _{RRM}	20	V			
Forward current (Average)	I _{F(AV)}	500	mA			
Non-repetitive peak forward surge current *	I _{FSM}	3	А			
Junction temperature	Tj	125	°C			
Storage temperature	T _{stg}	-55 to +125	°C			

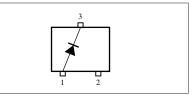
■ Absolute Maximum Ratings T_a = 25°





Marking Symbol: M4E

Internal Connection



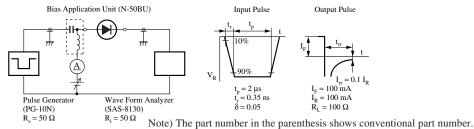
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V _{F1}	$I_F = 10 \text{ mA}$			0.3	V
	V _{F2}	I _F = 500 mA			0.5	
Reverse current	I _R	V _R = 10 V			30	μΑ
Terminal capacitance	Ct	$V_R = 0 V, f = 1 MHz$		60		pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 100 \text{ mA}$		5		ns
		$I_{rr} = 0.1 I_R, R_L = 100 \Omega$				

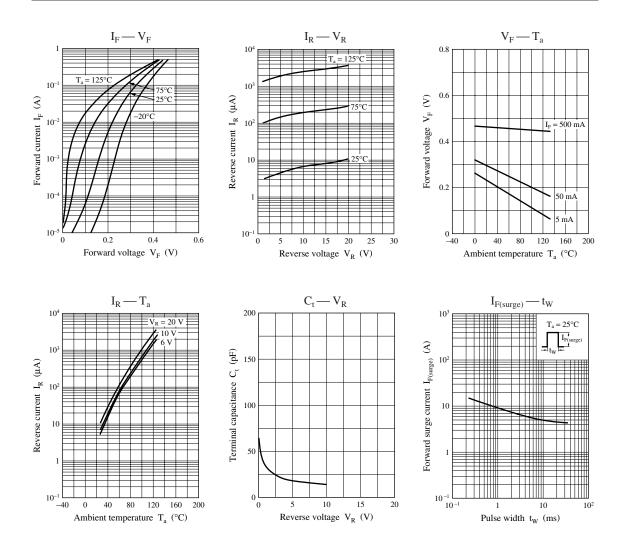
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

- 3. Absolute frequency of input and output is 400 MHz.
- 4. *: trr measurement circuit





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